AUTOMOTIVE

RoHS

COMPLIANT

HALOGEN

FREE



# Vishay General Semiconductor

# **Surface Mount Trench MOS Barrier Schottky Rectifier**

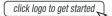
### TMBS® eSMP® Series



### MicroSMP (DO-219AD)



### **DESIGN SUPPORT TOOLS**





PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	2 A		
V <sub>RRM</sub>	150 V		
I <sub>FSM</sub>	30 A		
V <sub>F</sub> at I <sub>F</sub> = 2 A (125 °C)	0.68 V		
T <sub>J</sub> max.	175 °C		
Package	MicroSMP (DO-219AD)		
Circuit configuration	Single		

#### **FEATURES**





- Trench MOS Schottky technology
- Low forward voltage drop
- Low power loss, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

### TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications, in commercial, industrial, and automotive applications.

### **MECHANICAL DATA**

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, and RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

ALC-Q101 qualified

Terminals: Matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: Color band denotes the cathode end

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL V2P		UNIT	
Device marking code		2MC		
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V	
Maximum DC forward current	I <sub>F(AV)</sub> (1)	1.3	А	
	I <sub>F(AV)</sub> (2)	2	Α	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30	А	
Operating junction and storage temperature range	T <sub>J</sub> <sup>(3)</sup> , T <sub>STG</sub>	-40 to +175	°C	

#### Notes

- (1) Free air, mounted on recommended copper pad area
- (2) Mounted on 8.0 mm x 8.0 mm pad area
- $^{(3)}$  The heat generated must be less than the thermal conductivity from junction to ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.0 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.91	-	V
	I <sub>F</sub> = 2.0 A			1.33	1.41	
	I <sub>F</sub> = 1.0 A	T <sub>A</sub> = 125 °C		0.6	-	
	I <sub>F</sub> = 2.0 A			0.68	0.76	
Reverse current	V <sub>R</sub> = 100 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.001	-	- mA
		T <sub>A</sub> = 125 °C		0.25	-	
	V <sub>R</sub> = 150 V	T <sub>A</sub> = 25 °C		-	0.05	
		T <sub>A</sub> = 125 °C		0.5	2	
Typical junction capacitance	4.0 V, 1 MHz		CJ	100	-	pF

#### **Notes**

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL V2PM15			
Typical thermal resistance	R <sub>θJA</sub> (1)(2)	130	°C/W	
	R <sub>0JM</sub> (3)	20		

#### **Notes**

- $^{(1)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$  Free air, mounted on FR4 PCB, 2 oz. standard footprint,  $R_{\theta JA}$  junction to ambient
- (3) Mounted on PCB with 8.0 mm x 8.0 mm copper pad areas, R<sub>BJM</sub> junction to mount

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V2PM15-M3/H	0.006	Н	4500	7" diameter plastic tape and reel	
V2PM15HM3/H (1)	0.006	Н	4500	7" diameter plastic tape and reel	

#### Note

(1) AEC-Q101 qualified

## RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise noted)

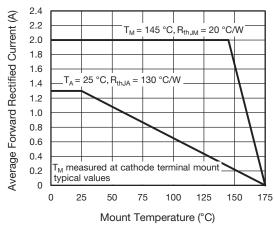


Fig. 1 - Maximum Forward Current Derating Curve

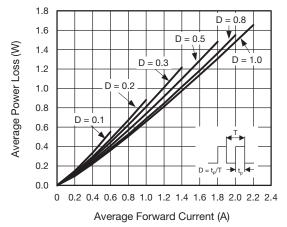


Fig. 2 - Average Power Loss Characteristics



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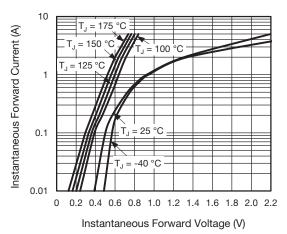


Fig. 3 - Typical Instantaneous Forward Characteristics

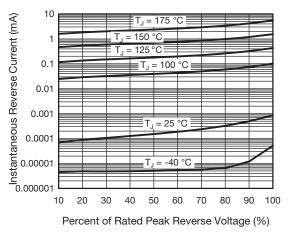


Fig. 4 - Typical Reverse Leakage Characteristics

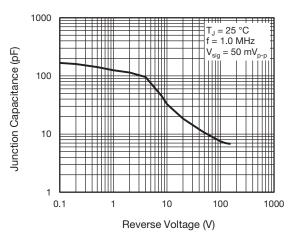


Fig. 5 - Typical Junction Capacitance

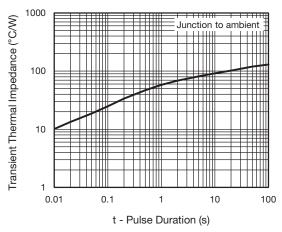
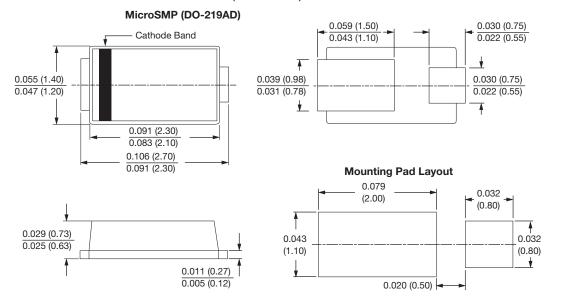


Fig. 6 - Typical Transient Thermal Impedance

### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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